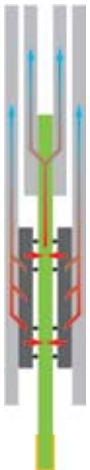




TW3X2G1600C9DHX G

The TW3X2G1600C9DHX G is a 2048MByte matched pair of DDR3 SDRAM DIMMs built using Corsair's latest high performance heat sink with Dual-Path Heat Xchange (DHX) technology. This part delivers outstanding performance in the latest generation of dual-channel DDR3-based motherboards. It has been tested extensively in popular DDR3 motherboards to ensure compatibility and performance at its rated speed. This memory has been verified to operate at 1600MHz at the low latencies of 9-9-9-24.



Dual-Path Heat Xchange Diagram

- Optimized fins to maximize ambient airflow through the module array
- Extruded aluminum heat sinks to maximize convective heat dissipation
- Dedicated PCB heat sink



TEST SPECS

- ▶ Each module pair is tested together at 1600MHz
- ▶ Tested and packaged in pairs
 - ➔ Packaged together immediately following system test
- ▶ Tested together at 1600MHz, Vdim = 1.80V, at latency settings of 9-9-9-24
- ▶ SPD programmed at:
 - ➔ JEDEC standard 7-7-7-20 values at 1066MHz

FEATURES

- ▶ 2048 Megabytes of DDR3 memory
 - ➔ Two matched CM3X1G1600C9DHX G modules
- ▶ Using DHX technology providing maximum cooling
- ▶ 100% tested at 1600MHz in high performance DDR3 motherboards
- ▶ Lifetime warranty

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Every part is tested in Corsair's factory at 1600MHz, but your actual results may vary depending on the overclocking margin of your CPU and motherboard. Newer motherboards may be used for production test as they become available. Corsair may periodically update the part with newer RAM revisions of same or greater performance. RAM used on the module may change without notice. © March 2008 Corsair Memory, Inc.